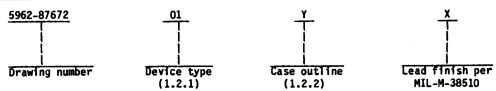
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<u>DISTRIBUTION STATEMENT A.</u> Approved for public release; distribution is unlimited. **DESC FORM 193**MAY 86

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1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type Generic number Circuit function

01 82188 Integrated bus controller

1.2.2 <u>Case outline</u>. The case outline shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter

Case outline

Y

D-10 (28-lead, $1/2^{m} \times 1 3/8^{m}$), dual-in-line package

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO

SIZE
A
CODE IDENT. NO. DWG NO.
14933
5962-87672
PAGE
2



2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

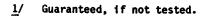
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design</u>, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Block diagram. The block diagram shall be as specified on figure 2.
 - 3.2.3 Case outline. The case outline shall be in accordance with 1.2.2 herein.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933		52-87672
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	<u></u>	т					Limi	ts	1
Test	Symbol		-55°C < V _{CC}	ndition T _C < + = 5 V ±	s 1/ 125 C 10%	Group A subgroup	i	Max	Unit
Input low voltage	VIL	 				1,2,3	5 <u>1</u> /	.8	Y
Input high voltage	A ^{IH}] 				1,2,3	2.0	Vcc+ 0.5 1/	V
Output low voltage	VOL	IOL	= 2 mA			1,2,3		.45	V
Output high voltage	νон	IOH	# -400 μA			1,2,3	2.4		V
Power supply current	Icc					1,2,3		100	mA
Input leakage current	ILI	0 V	< VIN < A	СС		1,2,3		±10	 μ Α
Output leakage current	I _I LO	 Only	V < V _{OUT} WR, RD a e-statable	nd DEN	pins are	1,2,3	 	±10 	μ А
CLK input low voltage	ACTI					1,2,3	5 1/	.6	٧
CLK input high voltage	ACHI					1,2,3	3.9	V _{CC} + 1.0 <u>1</u> /	٧
Input capacitance	CIN	See	4.3.1c			4	 	10	pF
I/O capacitance	c10	See	4.3.1c			4		20	pF
Clock period	tCLCL	 See 1	figures 3	and 4		9,10,11	125	 500 	ns
Clock low time	[‡] CLCH	T 				9,10,11	1/2 (t _{CLCL}) -7.5		ns
Clock high time	tchcl	T 			. •	9,10,11	1/2 (t _{CLCL}) -7.5		ns
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MILITARY DRA			SIZE		10 ENT. NO.	DWG NO.	5962-8767	2	
DEFENSE ELECTRONICS SUI DAYTON, OHIO		ER			REV	F	PAGE	4	

TABLE	I. Elec	trical perfor	mance c	haracteri	stics	- Continu	ied.		
Test	Symbol	l -55°C ⋅	onditio	+125°C		Group A subgrou		mits Max	Unit
ARDY active setup time	taryhcl	See figures 3	3 and 4	·		9,10,11	. 20	 	ns
ARDY hold time 2/	tCHARYL					9,10,11	. 15		ns
ARDY inactive setup time	^t arylch					9,10,11	. 35		ns
SRDY input setup time $3/$	^t SRYHCL					9,10,11	65,50		ns
STATUS active setup time	^t sych	_				9,10,11	55		ns
STATUS inactive setup time	tsxcl					9,10,11	50		ns
QSOI, QSII setup time	[‡] QI V CL	_				9,10,11	15		ns
HLDA setup time	^t havgy					9,10,11	50		ns
SYSHOLD asynchronous setup time	^t shycl					9,10,11	25	 	ns
RQ/GT input setup time 4/5/	^t GVCH	• :				9,10,11	0		ns
Status valid to ALE delay <u>6</u> /	t _{SVLH}					9,10,11		30	ns
ALE inactive delay	t _{CHLL}					9,10,11		30	ns
RD, WR active delay	t _{CLML}					9,10,11	10	70	ns
RD, WR inactive delay	^t CLMH					9,10,11	1 10	55	l ns
Status to DT/R delay <u>7</u> /	tsydty					9,10,11		30	ns
DT/R active delay <u>7</u> /	tCLDTY					9,10,11		55	ns
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DEFENSE ELECTRONICS SUPP DAYTON, OHIO	LY CENTE	R		REV		,	PAGE	5	
DESC FORM 193A FEB 86	<u> </u>		4	:				-	•

Test	[Symbo]		Co	onditio	ns		Group /	A	Lim	Unit	
lest		Conditions -55°C < T _C < +125°C V _{CC} = 5 V ±10%					subgro	ups [Min	Max	
DEN active delay	†CHDNV	 See f	igures	3 and 4			9,10,1	1	10	55	ns
DEN inactive delay 1/	tCHDNX	T 					9,10,1	1	10.	55	ns
QS00, QS10 delay	¢CLQ0V	T 					9,10,11	1	5	50	ns
Hold delay <u>1/5</u> /	tснну	<u> </u>			:		9,10,11			50	ns
SYSHLDA delay 5/	tCLSAV	T 					9,10,11	L		50	ns
RQ/GT output delay 5/	t _{CLGV}	T 		:			9,10,11	L I		40	ns
RO/GTO to hold delay 1/5/	t _{GVHV}	T 					9,10,11	l		50	ns
ALE active delay 6/	tCLLH	† 					9,10,11	I I		30	ns
Command enable delay	tAELCY	T 					9,10,11			40	ns
Command disable delay	tAEHCX	T ! !					9,10,11			40	ns
SRO output delay 5/8/	tCHRO	T ! 					9,10,11		5	30	ns
SRDY to SRO delay 8/	tSRYHRO	T 	•				9,10,11	- T		30	ns
CSIN to CSOUT delay	tcsisco	<u>[</u>					9,10,11	.		30	l ns
CLK low to $\overline{\text{CSOUT}}$ delay $\underline{1}/$	tCLCSOV						9,10,11	.	10		ns
CLK low to CSOUT inactive delay 1/	t _{CLCSOH}	 					9,10,11		10		ns
See footnotes on next page.	·	<u> </u>									
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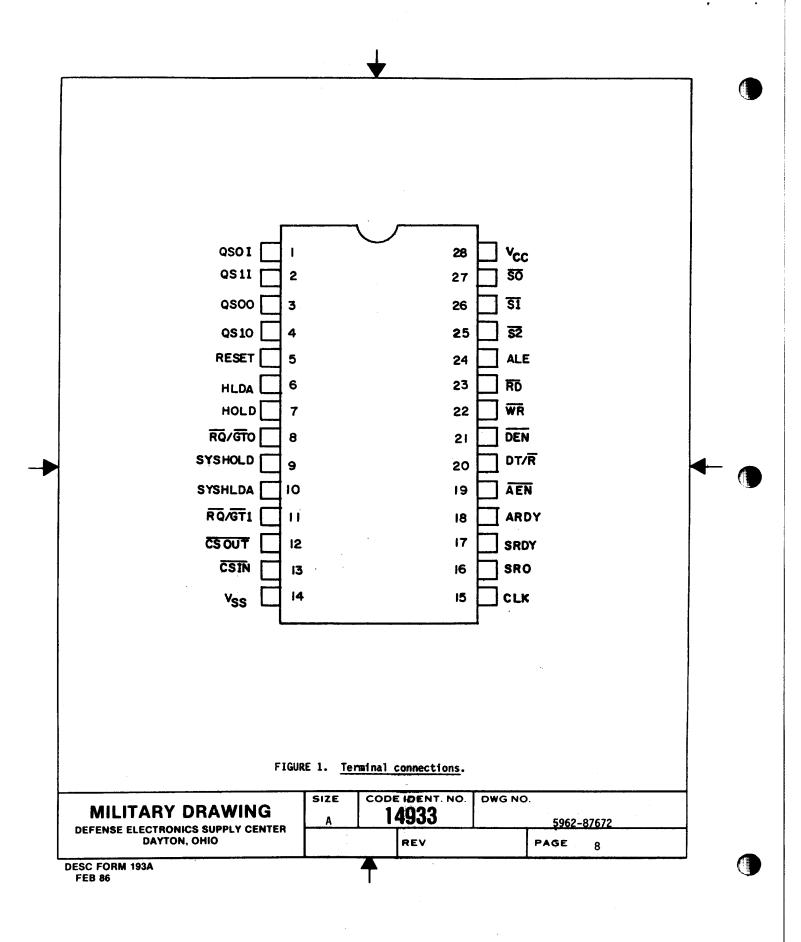


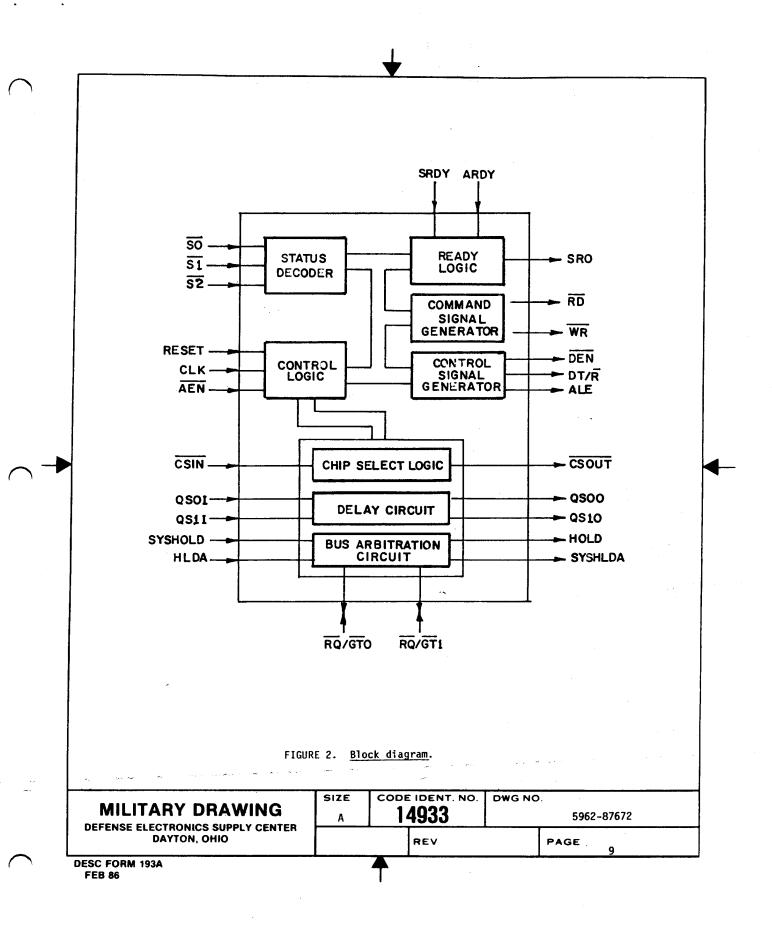
- 2/ The falling edge of ARDY must be synchronized to CLK.
- $\frac{3}{}$ t_{SRYHOL} = (80186's) t_{SRYCL} + 30 ns = 65 ns for 6 MHz operation and 50 ns for 8 MHz operation.
- 4/ Due to test equipment limitations, actual tested values may differ from those specified, but specified values are guaranteed.
- 5/ C_L = 20 pF to 100 pF.
- $\underline{6}/$ ALE will be asserted to the latest of t_{SVLH} and t_{CLLH}.
- 7/ DT/ \overline{R} will be asserted to the latest of t_{SVDTV} and t_{CLDTV}.
- 8/ SRO will be asserted to the latest of t_{CHRO} and t_{SRYHRO}.

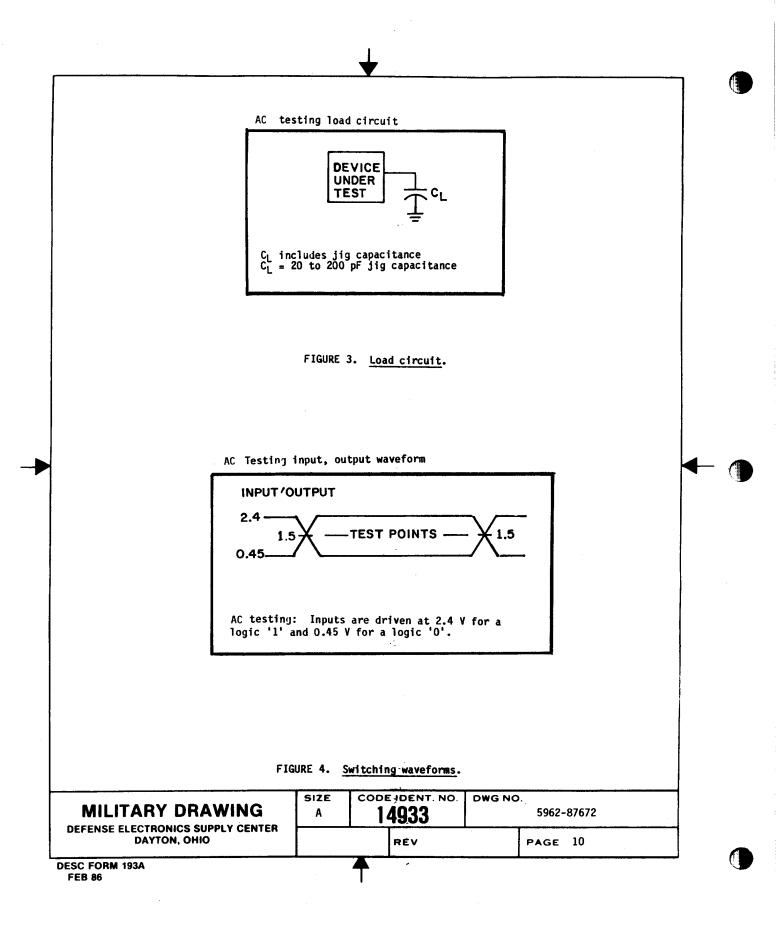
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO

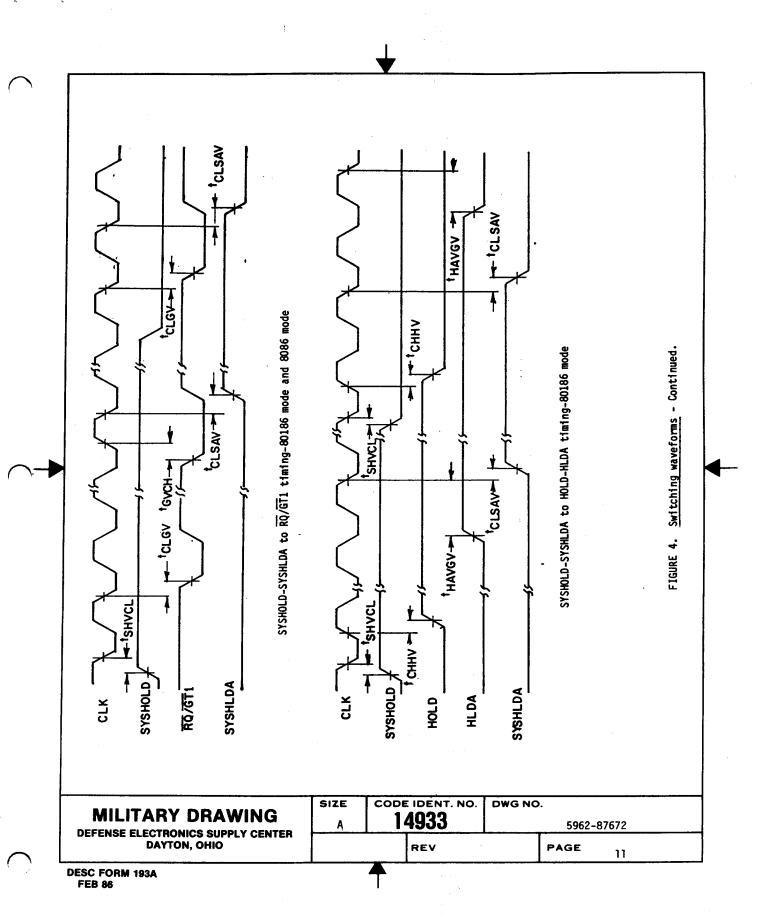
SIZE
CODE IDENT. NO. DWG NO.
14933
5962-87672

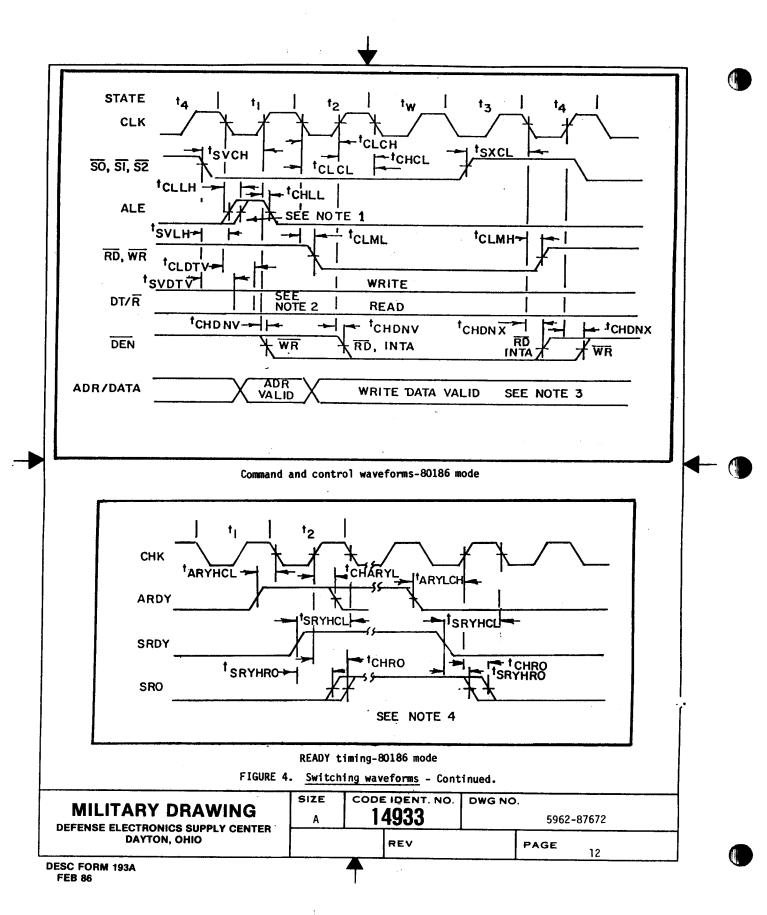
REV
PAGE
7

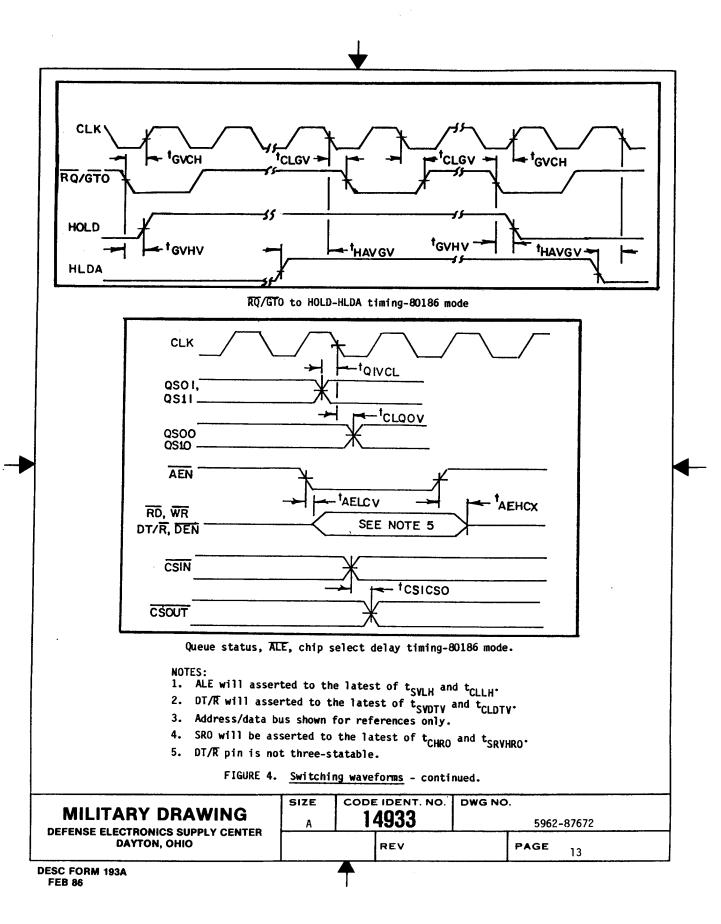












- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening.</u> Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 ($C_{\rm IN}$ and $C_{\rm IO}$ measurements) shall be measured only for the initial test and after process or design changes which may affect capacitance.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933	DWG NO. 5962-87672
		REV	PAGE 14

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	11*,2,3,7*,8,9, 110,11
Group A test requirements (method 5005)	1,2,3,7,8,9, 10,11
Groups C and D end-point electrical parameters (method 5005)	2, 8(Hot), 10
Additional electrical subgroups for group C periodic inspections	

^{*} PDA applies to subgroups 1 and 7.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

MILITARY DRAWING	SIZE A	14933		962-87672
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV	PA	NGE 15

6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /	Replacement military specification part number
5962-8767201YX	34649	MD82188/B	

 $\frac{1}{}$ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number 34649 Vendor name and address

Intel Corporation 5000 W. Williams Field Road Chandler, AZ 85224

MILITARY DRAWING

DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO

SIZE CODE IDENT. NO. DWG NO.

A 14933 5962-87672

REV PAGE 16

DESC FORM 193A FEB 86

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